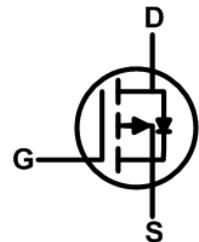
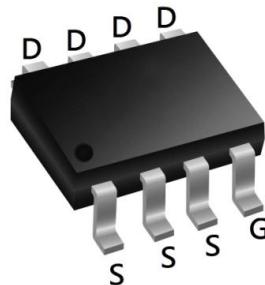


P-Ch 30V Fast Switching MOSFETs

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary

BVDSS	RDS _{ON}	ID
-30V	12mΩ	-11A

SOP8 Pin Configuration

Description

The XXW4435 is the high cell density trenched P-ch MOSFETs, which provide excellent RDS_{ON} and gate charge for most of the synchronous buck converter applications.

The XXW4435 meet the RoHS and Gree Product requirement 100% EAS guaranteed with full function reliability approved.

Absolute Maximum Ratings
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		-30	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	-11	A
		$T_C = 100^\circ\text{C}$	-8	A
I_{DM}	Pulsed Drain Current <small>note1</small>		-40	A
P_D	Power Dissipation	$T_A = 25^\circ\text{C}$	3.7	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		33.8	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

P-Ch 30V Fast Switching MOSFETs
Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-30\text{V}$, $V_{GS}=0\text{V}$,	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-1.0	-1.6	-2.5	V
$R_{DS(\text{on})}$ Note3	Static Drain-Source on-Resistance	$V_{GS}=-10\text{V}$, $I_D=-10\text{A}$	-	12	15	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=-5\text{A}$	-	18	27	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=-15\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	1330	-	pF
C_{oss}	Output Capacitance		-	183	-	pF
C_{rss}	Reverse Transfer Capacitance		-	156	-	pF
Q_g	Total Gate Charge	$V_{DS}=-15\text{V}$, $I_D=-5\text{A}$, $V_{GS}=-10\text{V}$	-	22	-	nC
Q_{gs}	Gate-Source Charge		-	1.0	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	1.8	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=-15\text{V}$, $I_D=-10\text{A}$, $V_{GS}=-10\text{V}$, $R_{GEN}=2.5\Omega$	-	9	-	ns
t_r	Turn-on Rise Time		-	13	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	48	-	ns
t_f	Turn-off Fall Time		-	20	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	-11	-	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-40	-	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=-15\text{A}$	-	-0.8	-1.2	V
t_{rr}	Reverse Recovery Time	$T_J=25^\circ\text{C}$, $V_{DD}=-24\text{V}$, $I_F=-2.8\text{A}$, $dI/dt=-100\text{A}/\mu\text{s}$	-	64	-	ns
Q_{rr}	Reverse Recovery Charge		-	25	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J=25^\circ\text{C}$, $V_{GS}=10\text{V}$, $R_G=25\Omega$, $L=0.5\text{mH}$, $I_{AS}=-12.7\text{A}$

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

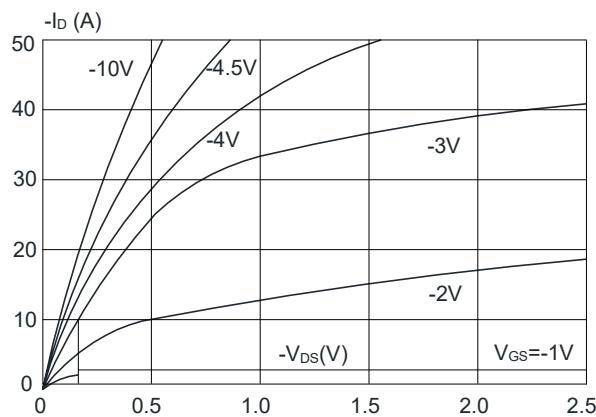


Figure 3: On-resistance vs. Drain Current

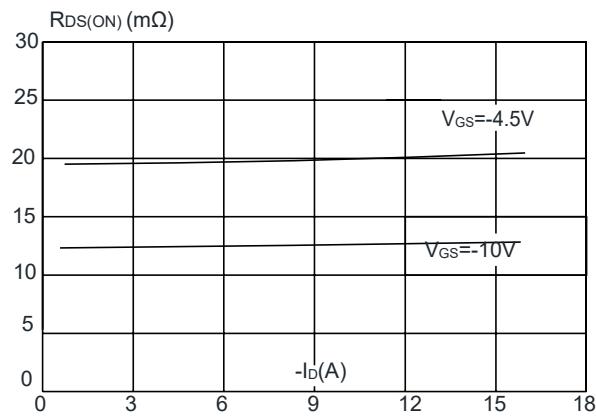


Figure 5: Gate Charge Characteristics

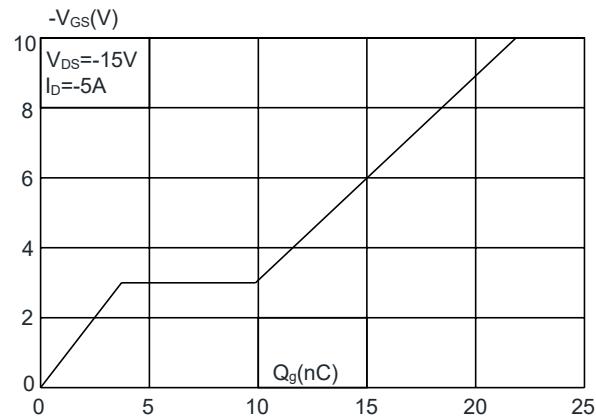


Figure 2: Typical Transfer Characteristics

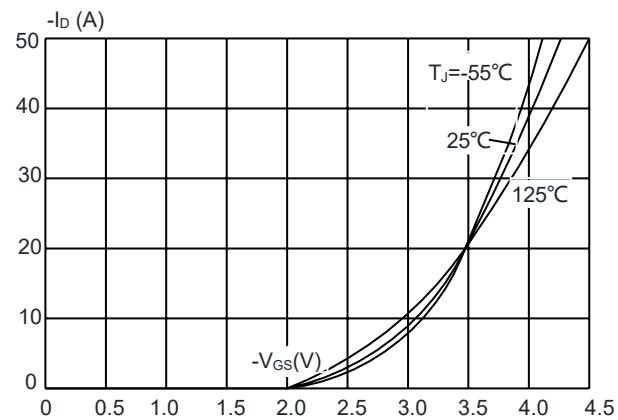


Figure 4: Body Diode Characteristics

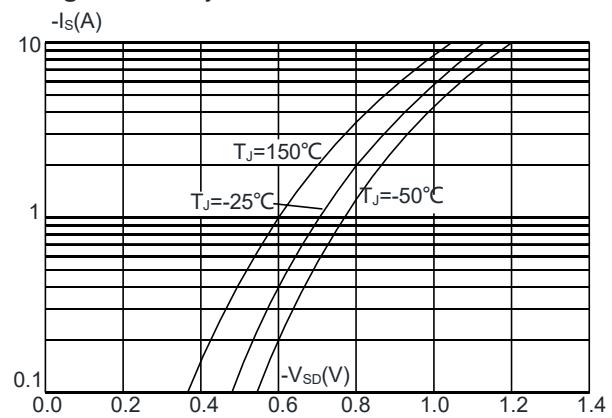
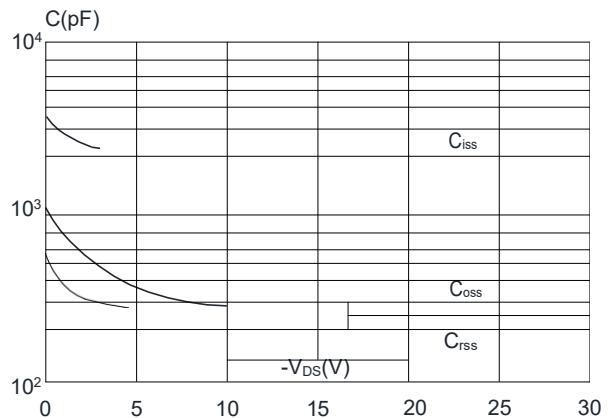


Figure 6: Capacitance Characteristics



P-Ch 30V Fast Switchin MOSFETs

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

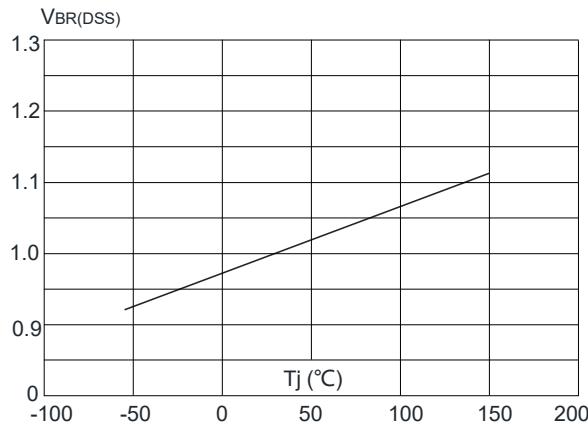


Figure 9: Maximum Safe Operating Area

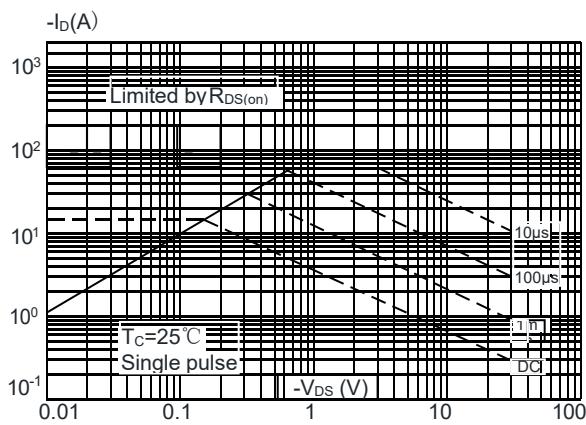


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

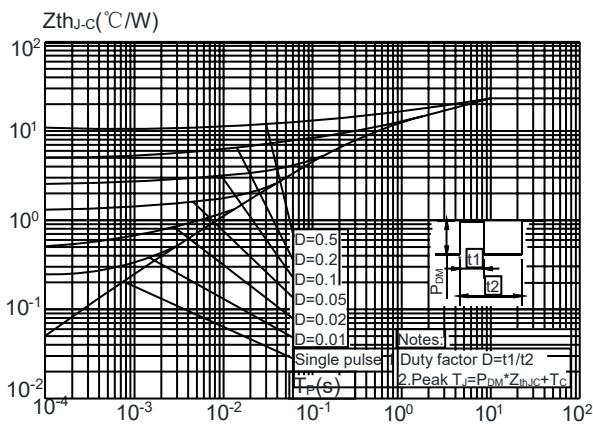


Figure 8: Normalized on Resistance vs. Junction Temperature

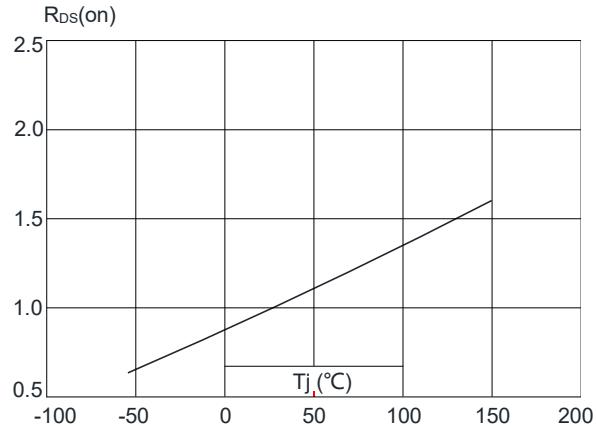
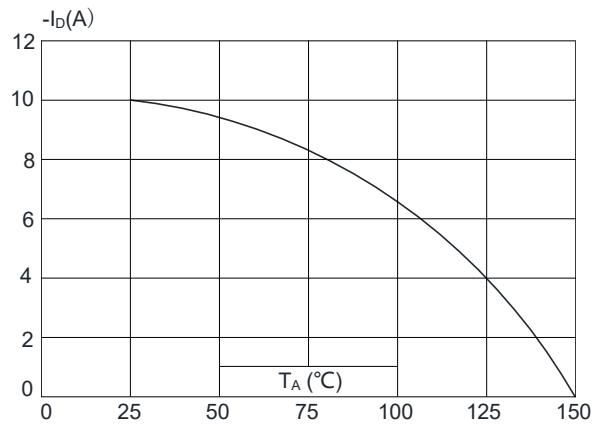
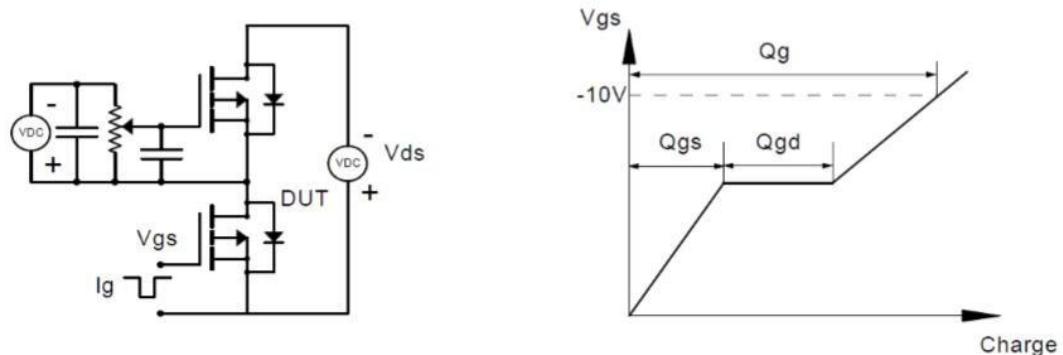


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

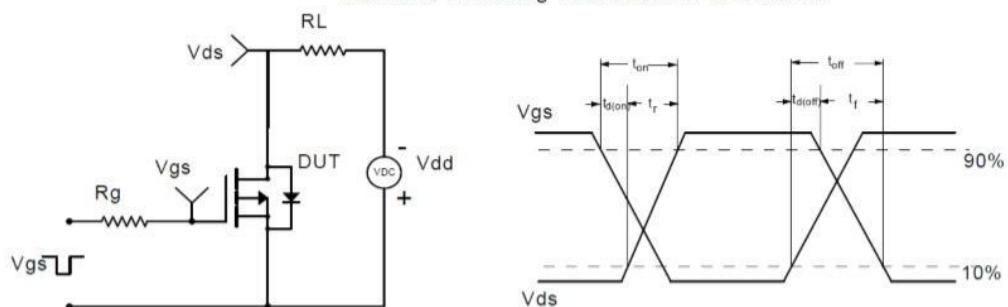


Test Circuit

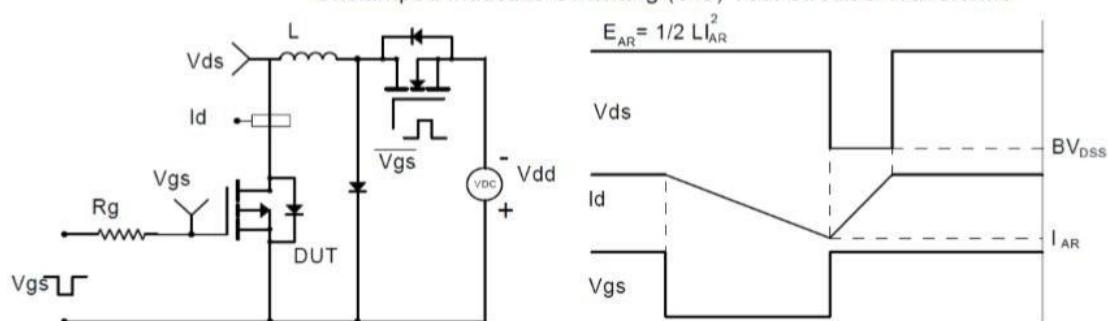
Gate Charge Test Circuit & Waveform



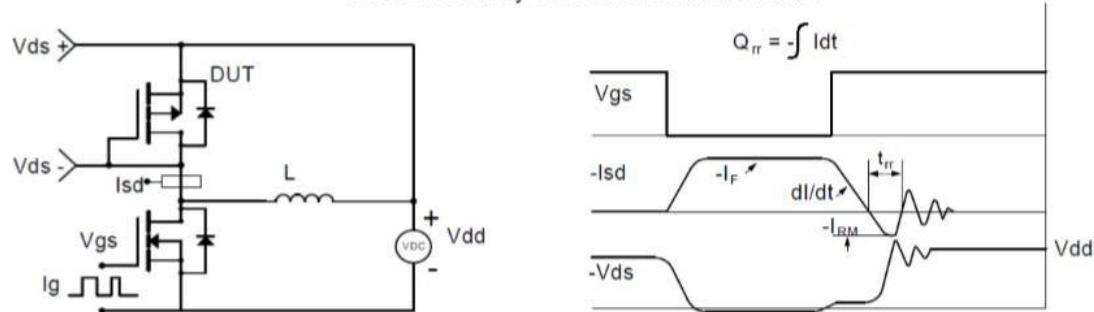
Resistive Switching Test Circuit & Waveforms

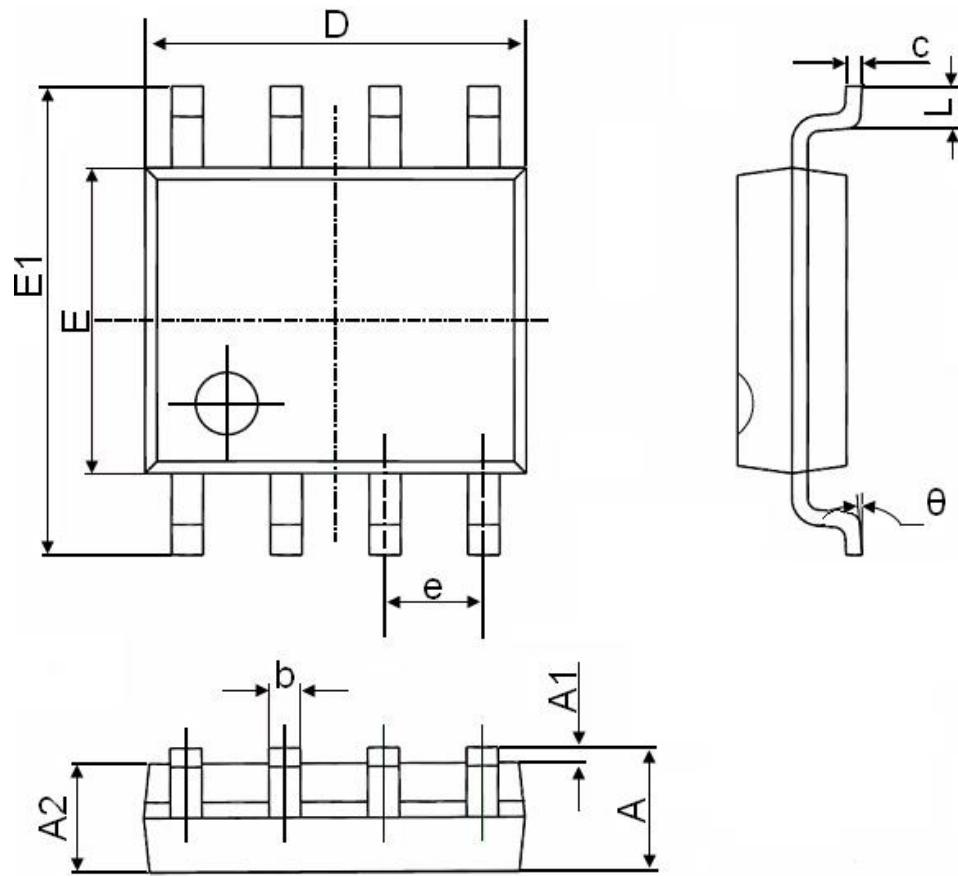


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



SOP-8 Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°